
CHALLENGES OF HIGH-SPEED EUV DEFECT INSPECTION

MP0601: Short Wavelength Laboratory Sources
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EUROPEAN COOPERATION IN SCIENCE AND TECHNOLOGY

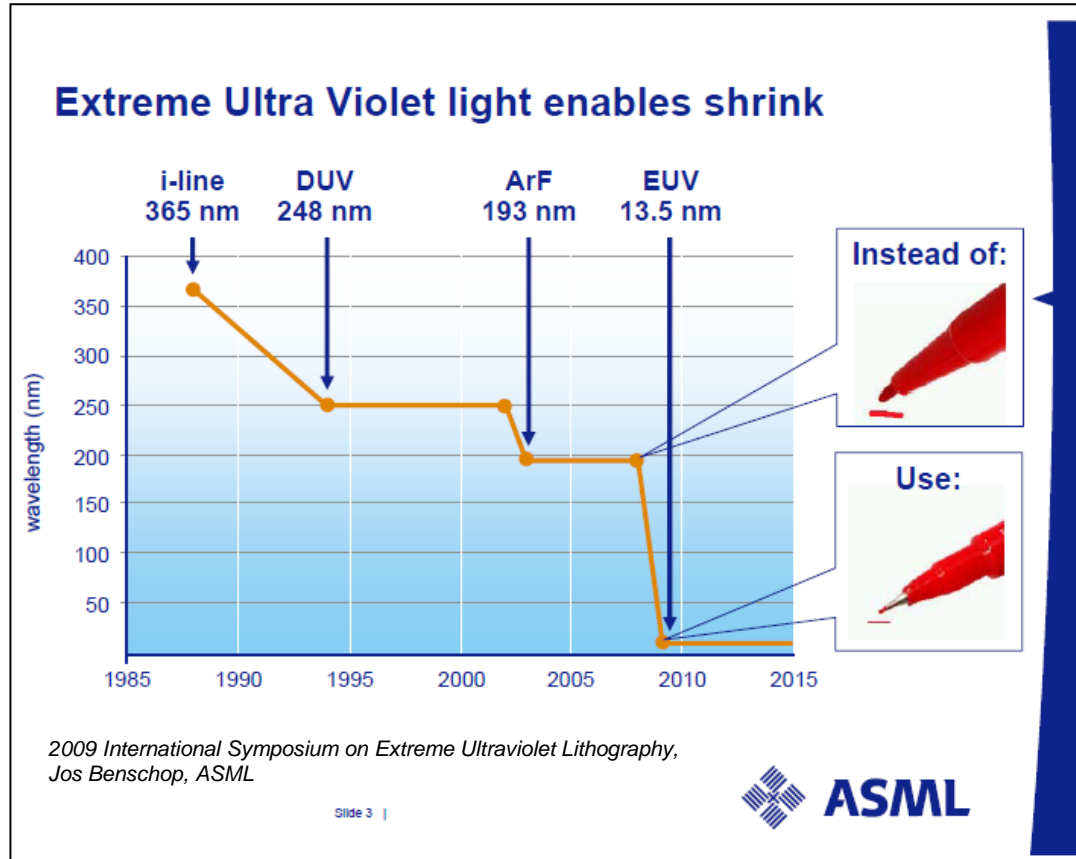


Outline

1. Motivation
2. Experimental setup
3. Experimental results
4. Limitations
5. Alternative detector concepts
6. Extendability
7. Conclusion & Outlooks

1. Motivation

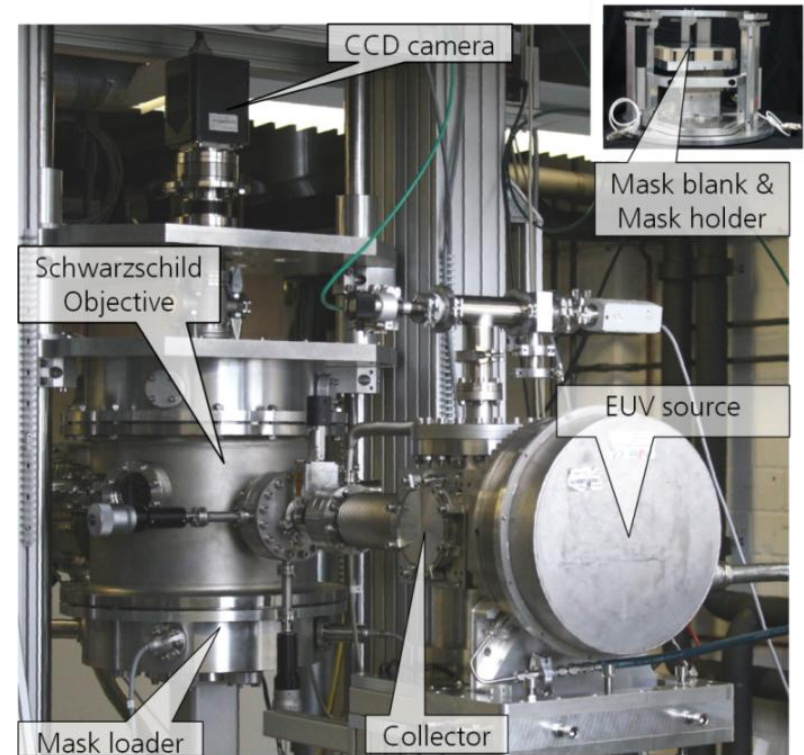
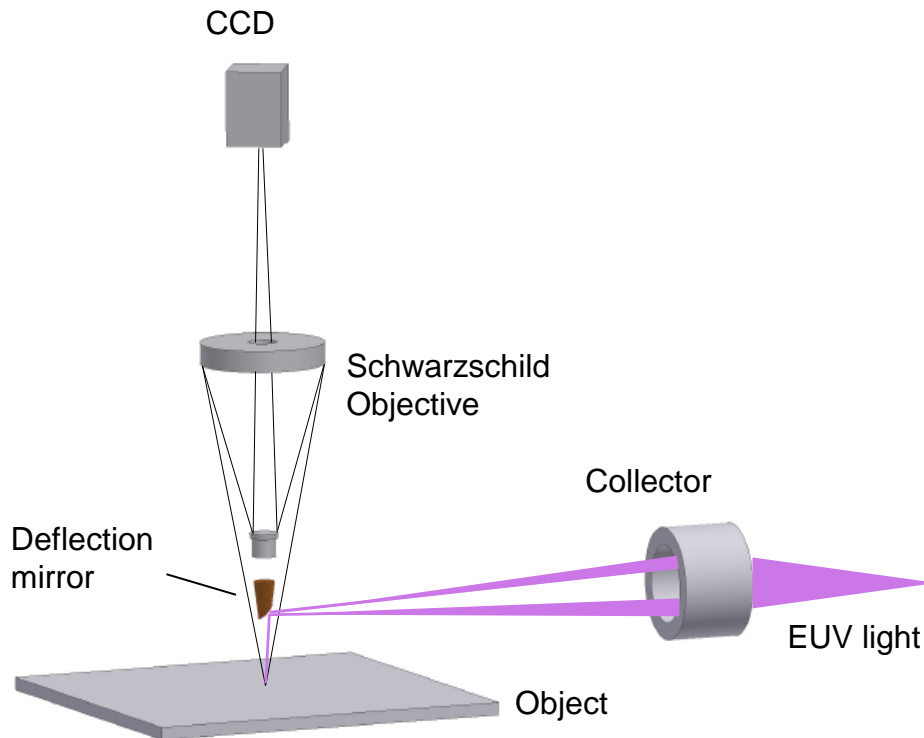
- Lithography => smaller structures (2011: 22nm HP) => shorter wavelength



1. Motivation

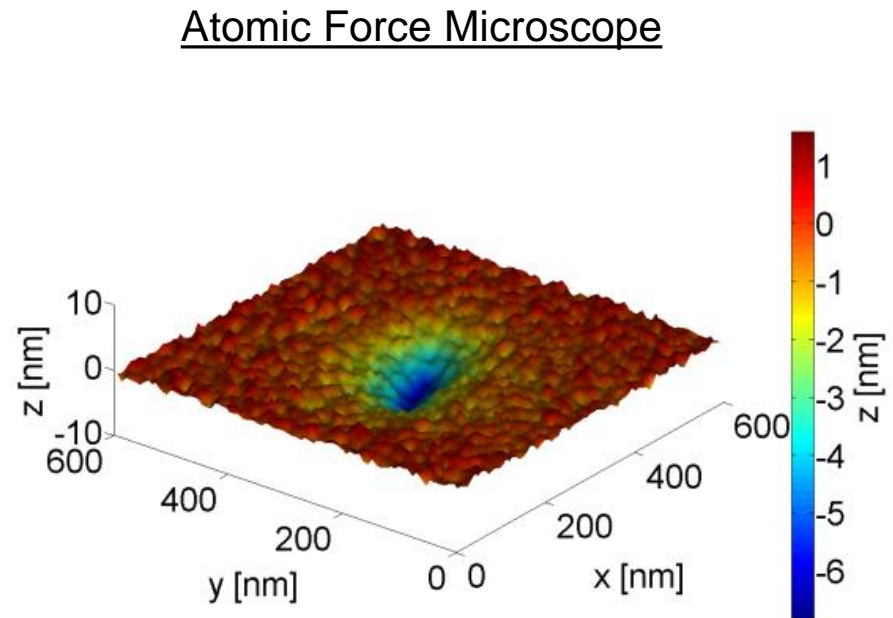
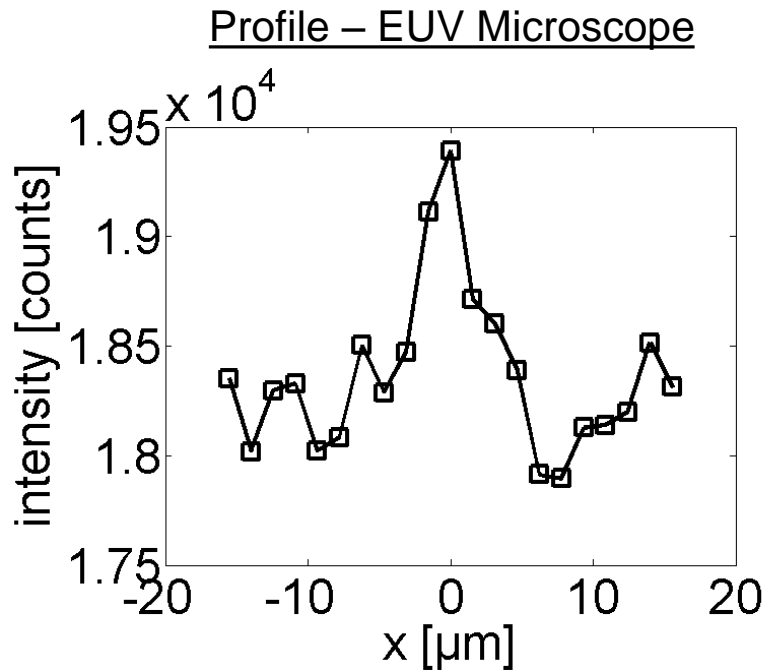
- Transition to EUV (13.5nm) => fundamental changes:
 - Vacuum required
 - No transmission masks, due to short penetration depth ($<1\mu\text{m}$)
=> reflection masks => multilayer mirrors
- Masks => mask blanks => both: defect free => critical defect size: 30nm
- Mask blank: $150\times 150\text{mm}^2$ ($143\times 143\text{mm}^2$ to inspect), inspection time $\leq 45\text{min}$
 - Resolving inspection => great sensitivity to defects, but $t_{\text{inspection}} \cong 2\text{ month}$
 - Inspect with large FOV => $t_{\text{inspection}}$ gets short, but sensitivity drops
- solution: sensitivity to small defects (=> dark field mode) but low resolution (=> big FOV), zooming option as a 2nd inspection step
- Parameters of: source/collector, object, objective, detector
=> **which are suitable for the task?**

2. Experimental setup



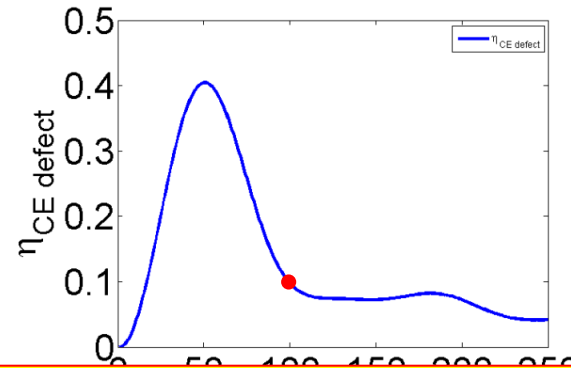
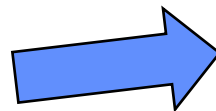
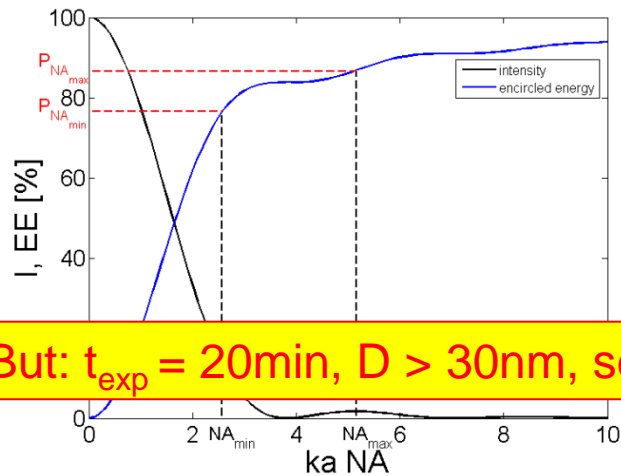
3. Experimental results

- Programmed structures (bumps and pits) and natural defects both on multilayer mirrors investigated by EUV microscope and characterized by Atomic Force Microscope
- Smallest structure: diameter = 45 nm, depth = 7 nm (equivalent sphere)



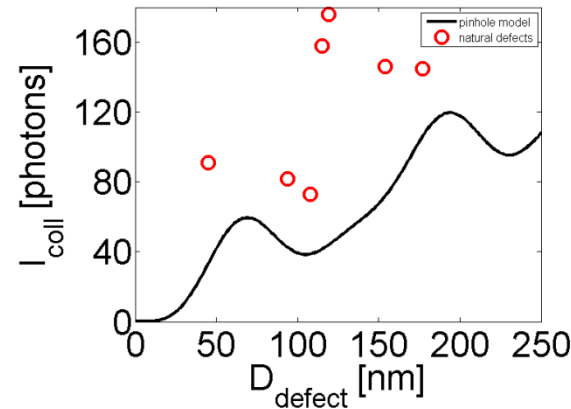
3. Experimental results

Pinhole approach for simulation of defects scattering distribution:



But: $t_{exp} = 20min$, $D > 30nm$, scanable area $25 \times 25mm^2$, **system not suitable!**

Comparison between experiment and simulation:



4. Limitations

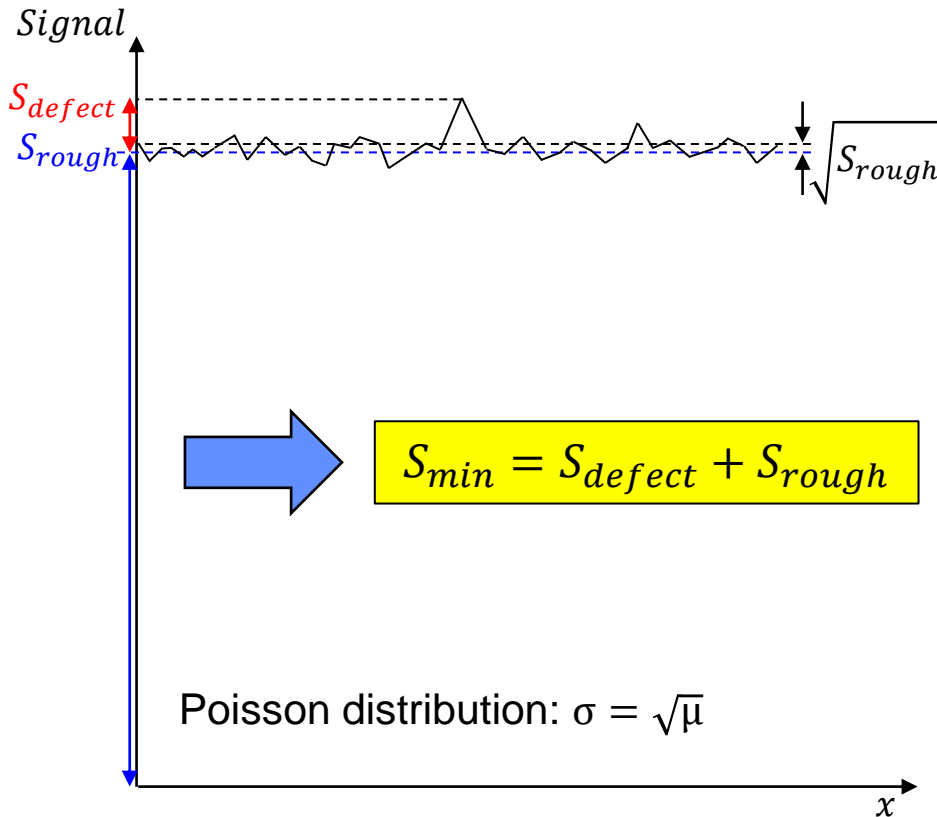
Three main categories can limit the tools performance due to the industrial requirements:

- 1) **Sensitivity** (object roughness, objective collection efficiency)
- 2) **Scan rate** (Sample mechanics, detector read out speed)
- 3) **Light flux** (source power, collector efficiency)

Parameter	Worst case	Expected case	Best case
η_{QE}		0.40	0.60
$\eta_{scatt-flare}$	0.02	0.015	0.01
$\eta_{scatt-defect}$		0.40	
$\eta_{collect-flare}$	0.15	0.20	0.25
$\eta_{collect-defect}$	0.20	0.25	0.30
R_{SO}		0.36	
$d_{pixel} [\mu m]$		13	
R_{defl}		0.45	
T_{filter}		0.30	
T_{gas}		0.70	
R_{coll}		0.45	
$\varphi_{obj-coll} [^\circ]$		5	
M_{coll}		6	
$d_{source} [\mu m]$		400	
$P_{source} [W/2\pi/2\%b.w.]$		30	

4. Limitations

1) Sensitivity:



$$SNR = \frac{S_{defect}}{\sqrt{S_{rough}}}$$

Rose criteria: $SNR \geq 5$

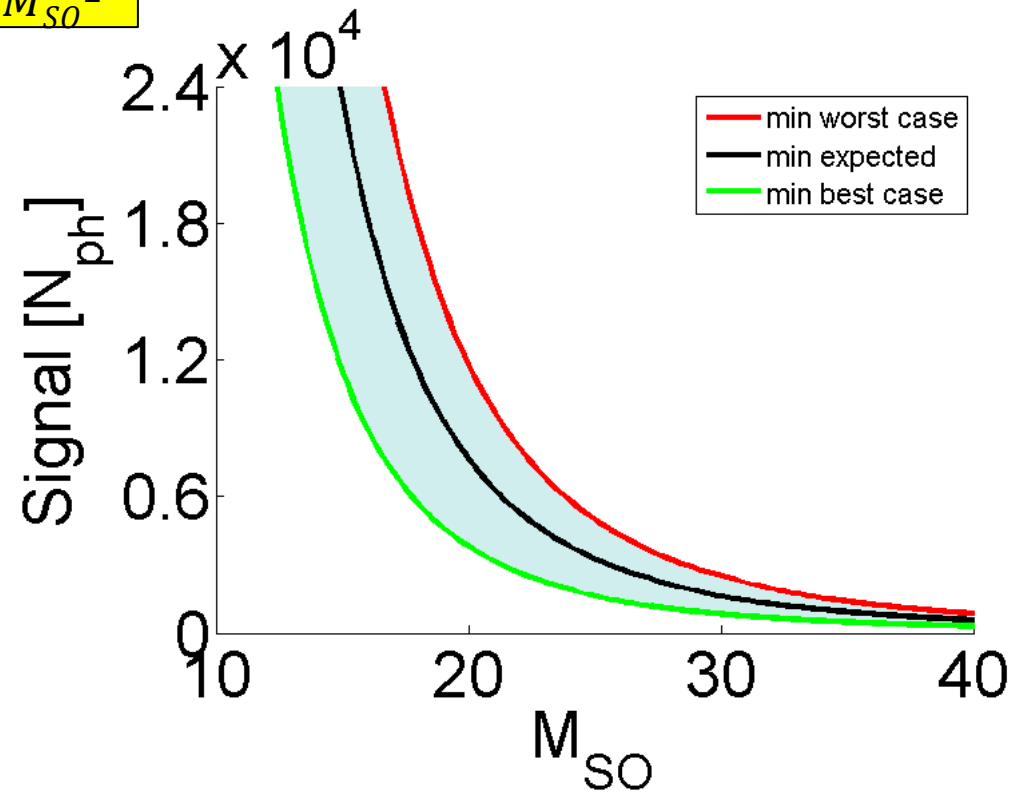
$$S_{defect} \geq SNR \cdot \sqrt{S_{rough}}$$

$$S_{min} \propto \frac{1}{M_{SO}^4} \quad \text{Scanspeed} \propto M_{SO}^2$$

Which is the optimal M_{SO} ?

4. Limitations

$$S_{min}(M_{SO}) = \frac{1}{SNR^2} \cdot A^2 \cdot \frac{1}{M_{SO}^4} + A \cdot \frac{1}{M_{SO}^2}$$



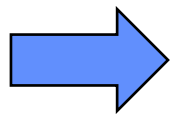
$$A = \frac{SNR^2 \cdot \eta_{SE_rough} \cdot A_{pix}}{\eta_{SE_defect} \cdot A_{defect}} \cdot \frac{\eta_{CE_rough}}{\eta_{CE_defect}}$$

4. Limitations

Detector dynamic range: 16bit:

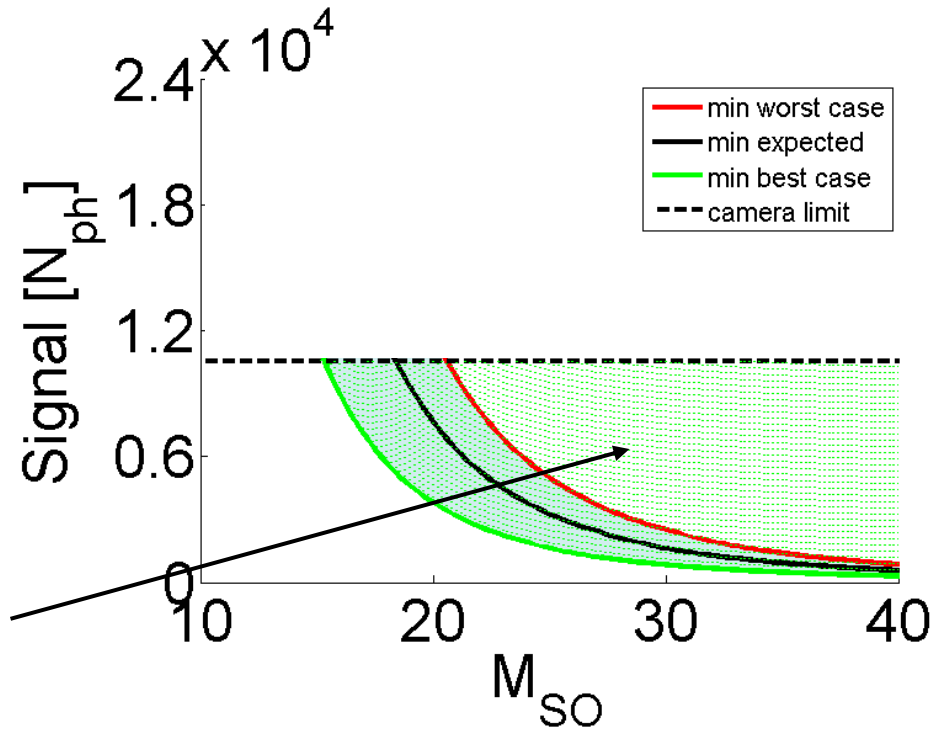
$$16 \text{ bit} = 2^{16} = 65536$$

$$\text{typical XUV CCD: } \frac{\text{counts}}{\text{ph}} \approx 6$$



$$S_{\min}(M_{SO}) \leq 10561$$

workable area

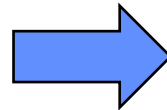


4. Limitations

2) Scan rate (SR):

Required:

$$SR_{req} = \frac{A_{blank}}{A_{FOV} \cdot t_{blank}} = \frac{M_{SO}^2 \cdot A_{blank}}{A_{pix} \cdot N_{pix} \cdot t_{blank}}$$

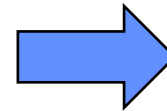


$$SR_{req}(M_{SO}) \propto M_{SO}^2 \quad \text{unit: fps}$$

reference: 1 MP camera

Sample Movement speed:

$$SR_{table} = \frac{1}{t_{exp} + t_{step}} \quad t_{exp} \Rightarrow 0$$



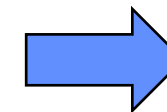
$$SR_{table_max}(M_{SO}) = 37fps^*$$

* concerning a commercial movement table with a step size of 1mm and a load of 1kg

Detector read out speed:

commercial full frame CCD: 4.6 fps

custom made frame transfer CCD: 9.8 fps



$$SR_{detector_max}(M_{SO}) = 9.8fps$$

4. Limitations

$$SR_{req}(M_{SO}) \propto M_{SO}^2$$

$$SR_{table_max}(M_{SO}) = 37 \text{ fps}$$

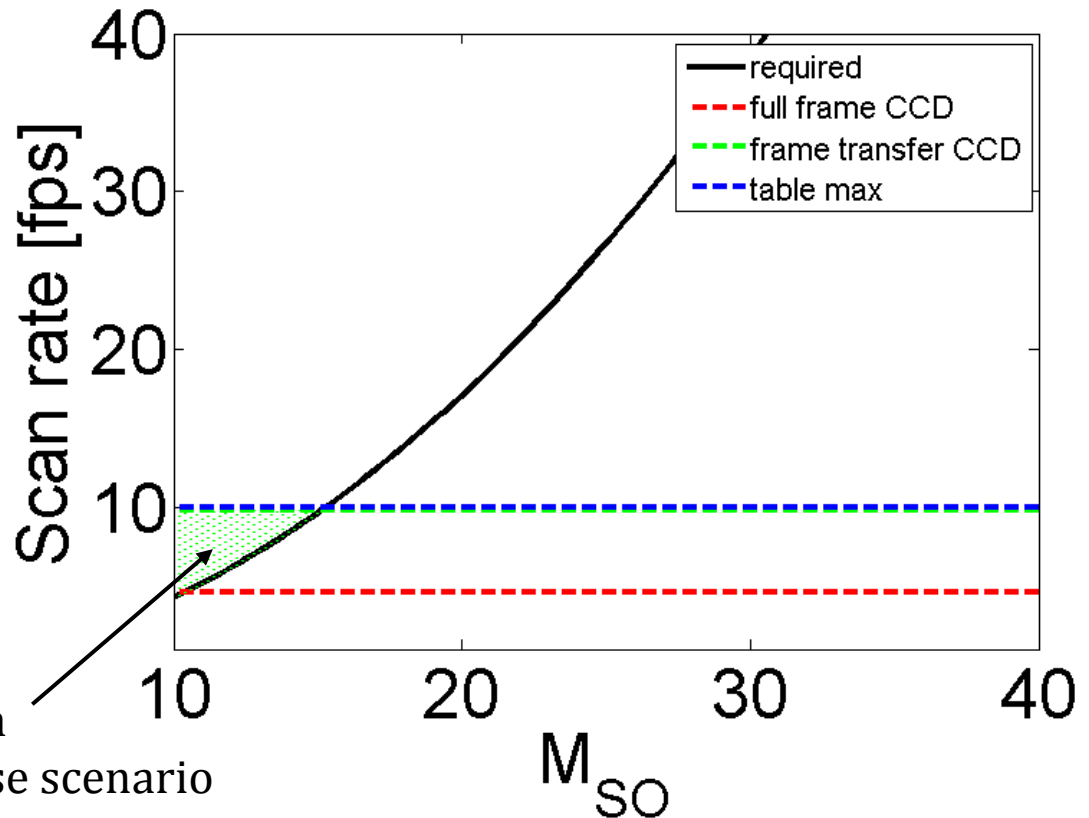
$$SR_{detector_max}(M_{SO}) = 9.8 \text{ fps}$$

$$SR_{table} = \frac{1}{t_{exp} + t_{step}}$$

$$t_{exp} = 0 \text{ ms}$$

$$t_{exp} = 73 \text{ ms}$$

usable area
for best case scenario



4. Limitations

3) Light Flux:

$$S_{source}(M_{SO}) = B \cdot C_{rough} \cdot \frac{1}{M_{SO}^2} + B \cdot C_{defect}$$

$$SR_{table} = \frac{1}{t_{exp} + t_{step}}$$

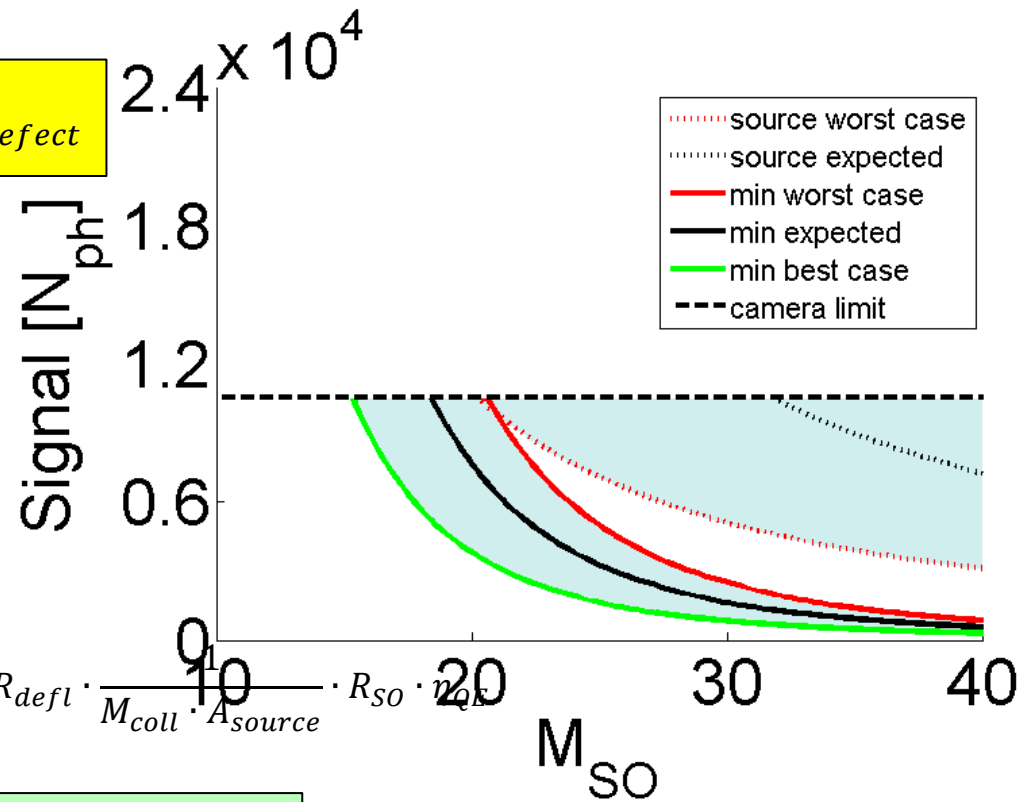
$$t_{exp} = 8 \text{ ms}$$

$$B = N_{ph_source} \cdot T_{gas} \cdot \eta_{CE_coll} \cdot R_{coll} \cdot T_{filter} \cdot R_{defl} \cdot \frac{1}{M_{coll} \cdot A_{source}} \cdot R_{SO} \cdot \eta_{det}$$

$$C_{rough} = A_{pix} \cdot \eta_{SE_rough} \cdot \eta_{CE_rough}$$

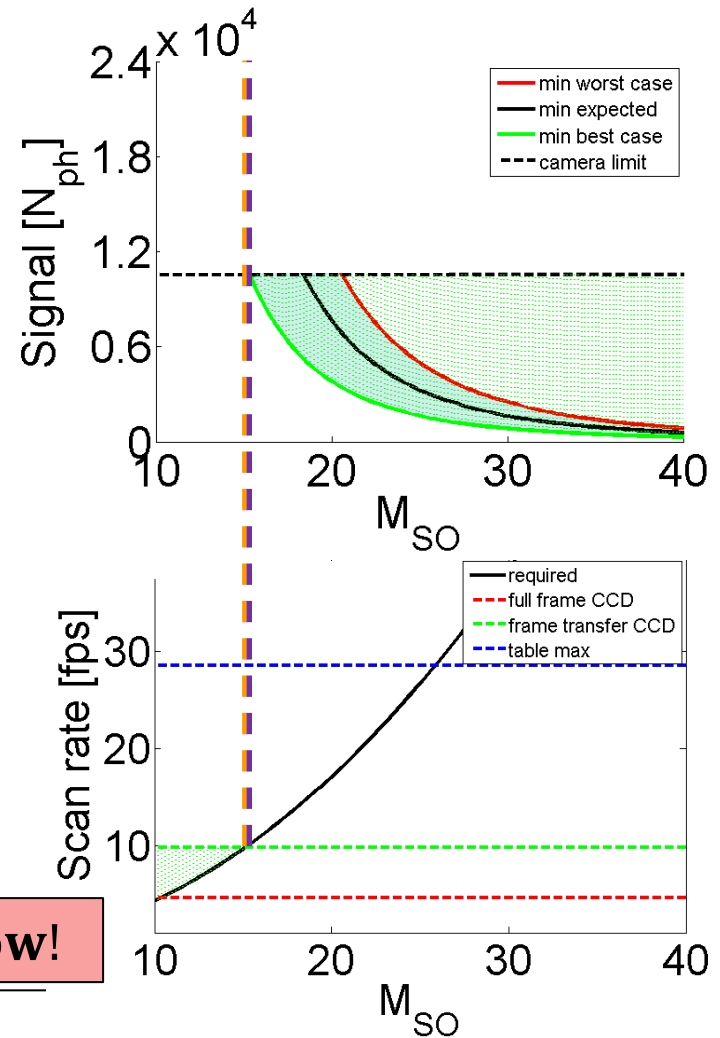
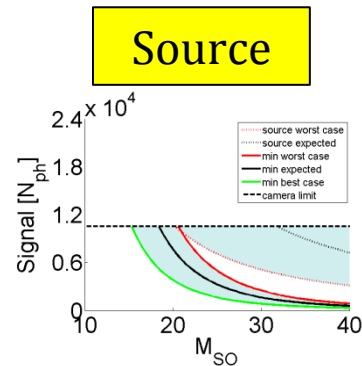
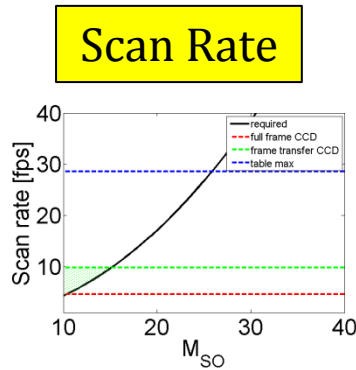
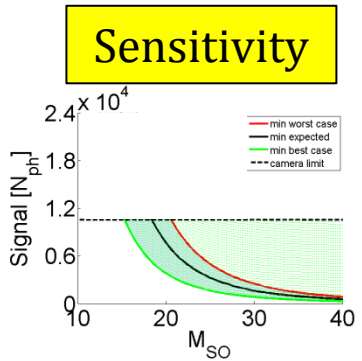
⇒ adapted to sensitivity requirement!

$$C_{defect} = A_{defect} \cdot \eta_{SE_defect} \cdot \eta_{CE_defect}$$



4. Limitations

Process window:



no process window!

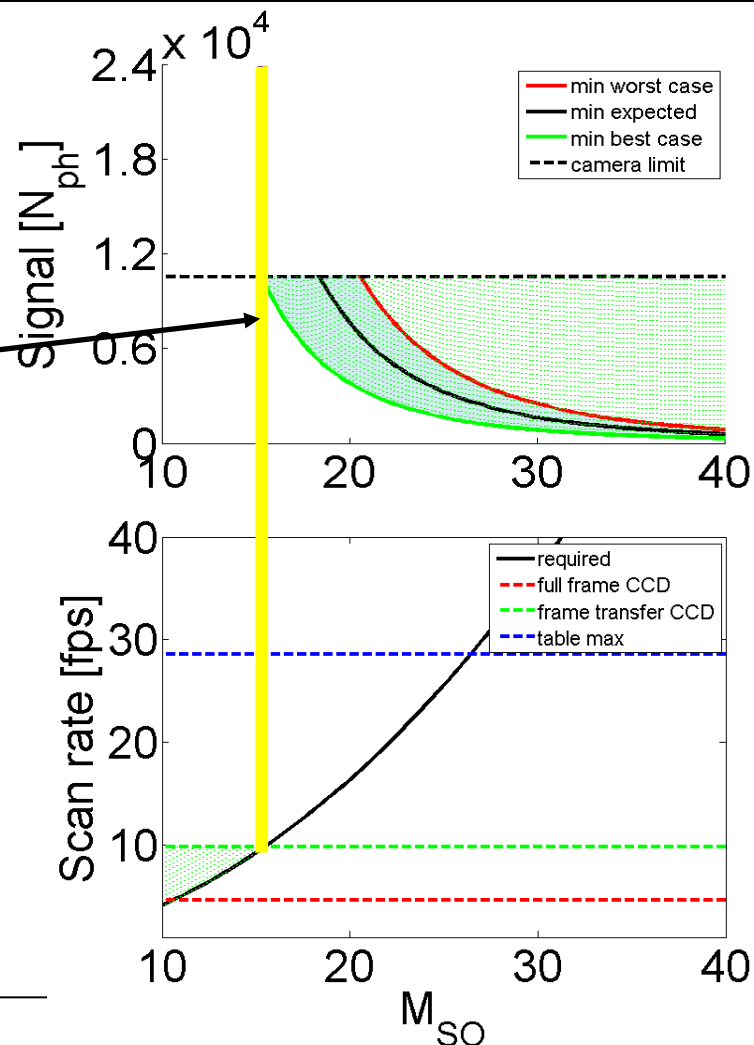
4. Limitations

No window achieved – what now?

- Required scan time: 45min
=> expand to 47min:

tiny process window
 $15.22 < M_{SO} < 15.42$

- But only counts for best case scenario!
- Limitation is detector read out speed and sensitivity
 - a) smoother sample
 - b) faster camera

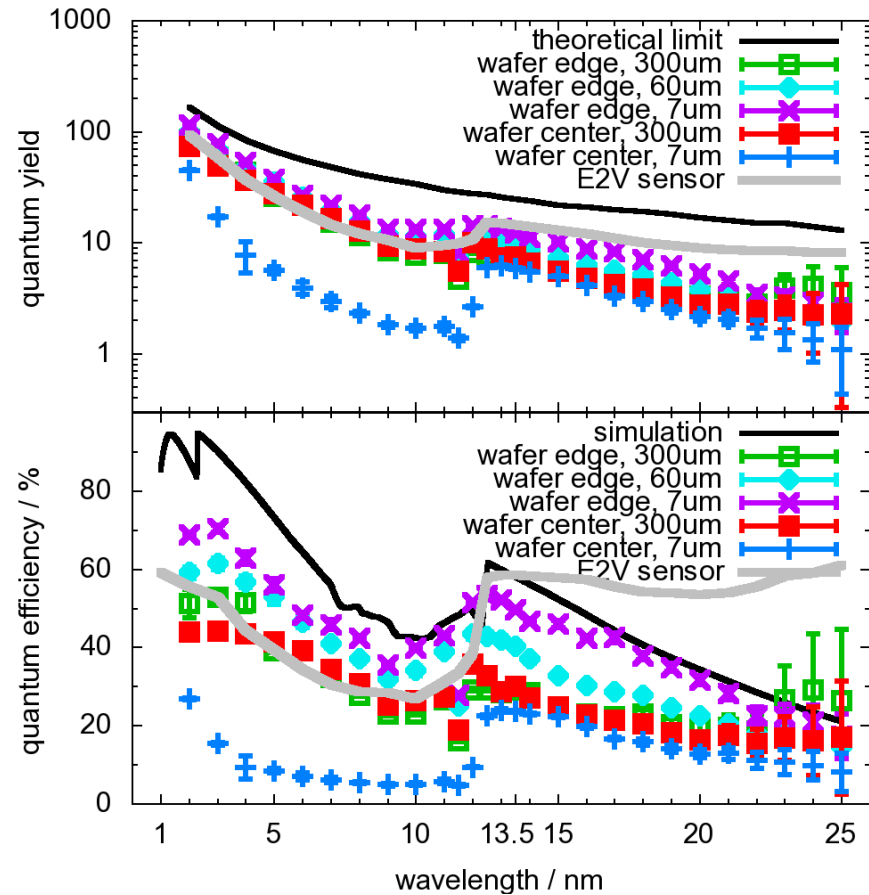
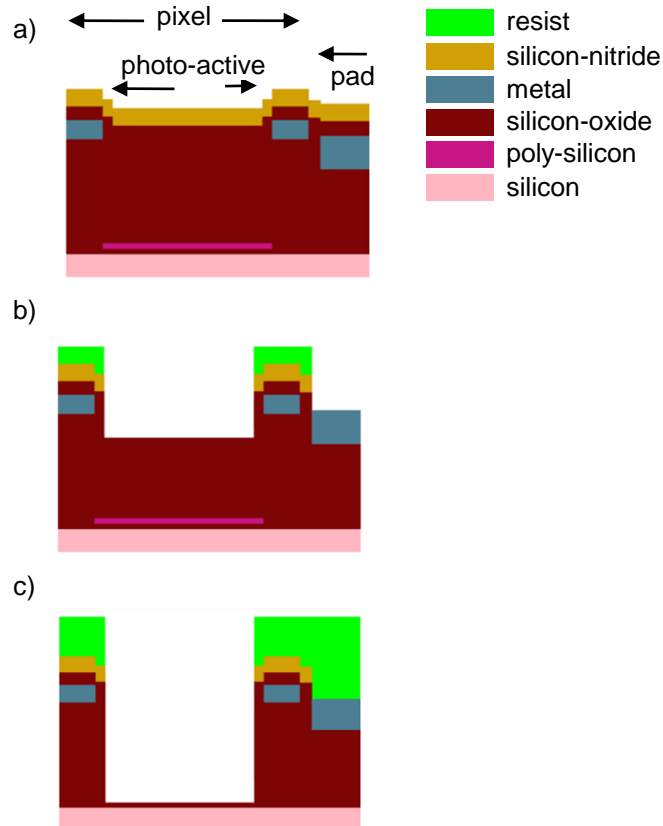


5. Alternative detector concepts

Concept	Price [k€]	Read out [fps]	QE [%]	Spatial resolution [μm]	Pixel Well Depth [ke ⁻]	Noise [e ⁻ rms] @ $t_{\text{exp}}=100\text{ms}$	Remarks
XUV CCD full frame (Andor iKon-M)	21	4.6	40-60	13	100	20	
XUV EMCCD frame transfer (Andor, custom made)	100	9.8	40-60	13	100	1	
XUV CCD Time Delay Integration ¹	-	6 ^a	-	-	-	-	- Complex synchronization
VIS CCD (Andor Clara) + scintillator ² + objective ²	14	21	2.1	6.5	18	7	
VIS sCMOS (Andor Neo) + scintillator ² + objective ²	17	553	3.6	6.5	25	1	- Fill factor (?)
VIS sCMOS (Andor Neo) + scintillator ² + fiber coupler (Proxitronic)	22	553	5.3	6.5	25	1	- Fill factor (?)
VIS sCMOS (Andor Neo) + Micro Channel Plate (Del Mar Photonics)	10-20	553	10-20	30	25	1	- Complex periphery, Fill Factor (?)
backside illuminated XUV wide bandgap CMOS ³	-	>200 ^b	5 ^c	10	-	-	+ no VIS filter, no cooling, - fill factor (?)
backside illuminated XUV backthinned CMOS Hybrid ⁴	-	1	30	10	-	25-33	- Fill factor (?)
frontside illuminated XUV open electrode CMOS ⁵	<10	245.8	25-55	12	200	116	- Fill factor 50%

5. Alternative detector concepts

Open Electrode CMOS:



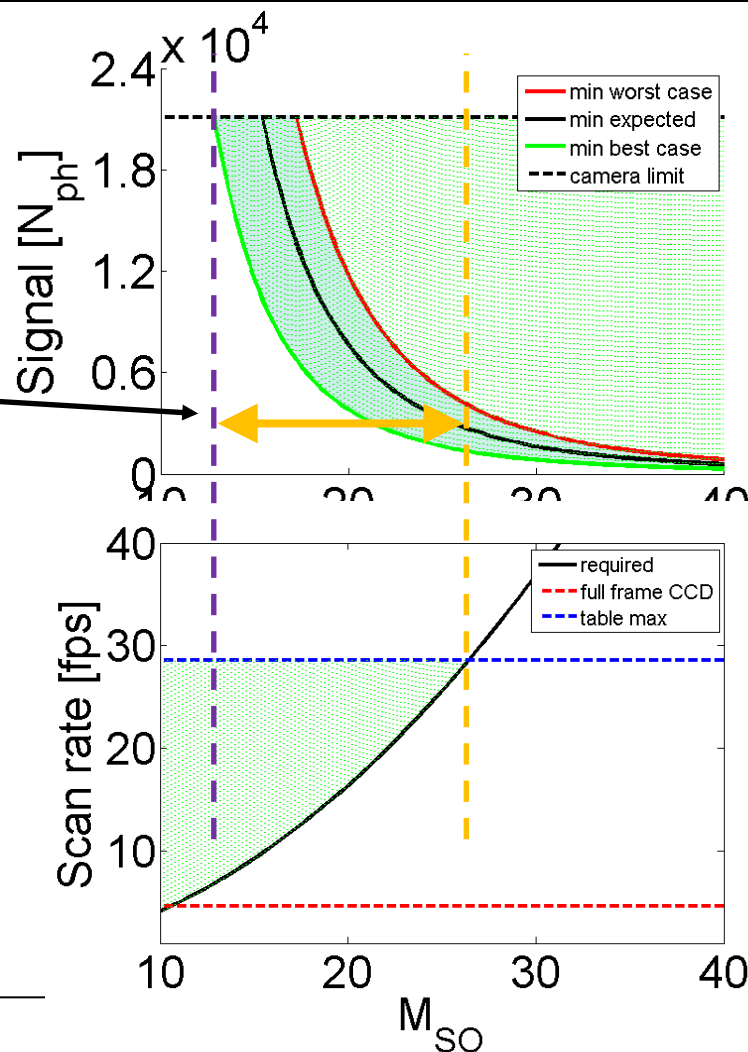
4. Limitations

Process window with DOSE camera:

- $N_{ph,max} \approx$ twice higher
- Scanrate \approx 25x higher

large process window!

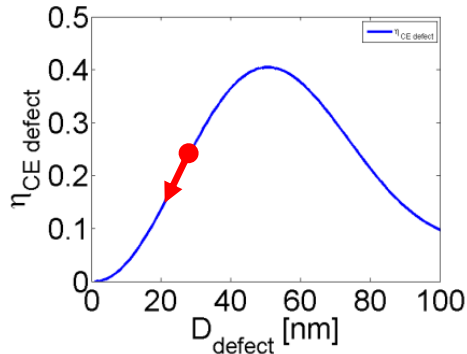
- 45min achievable
- Process window works for all scenarios
- Limitations now: sensitivity and sample scan speed



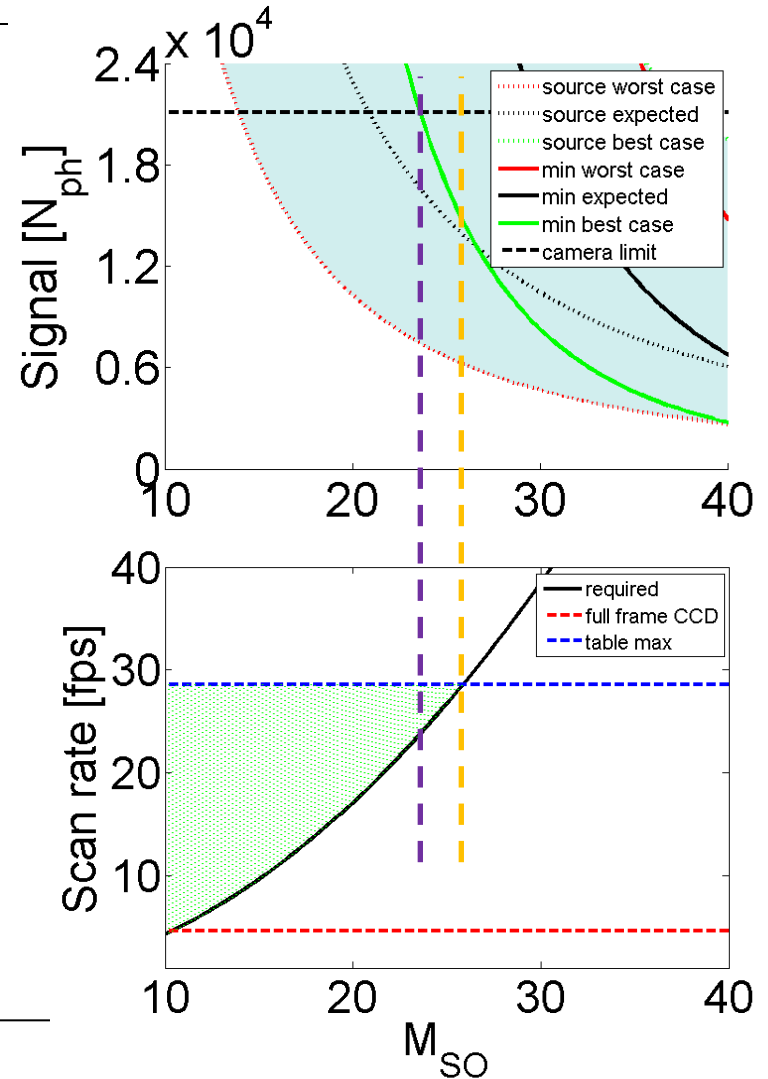
6. Extendability

Next critical defect size: 20nm

- Change in η_{CE_defect} :



- Scanrate remains the same
- Signal is shifted to higher M_{SO}
- Process window only work for best case scenario => adaptations required...



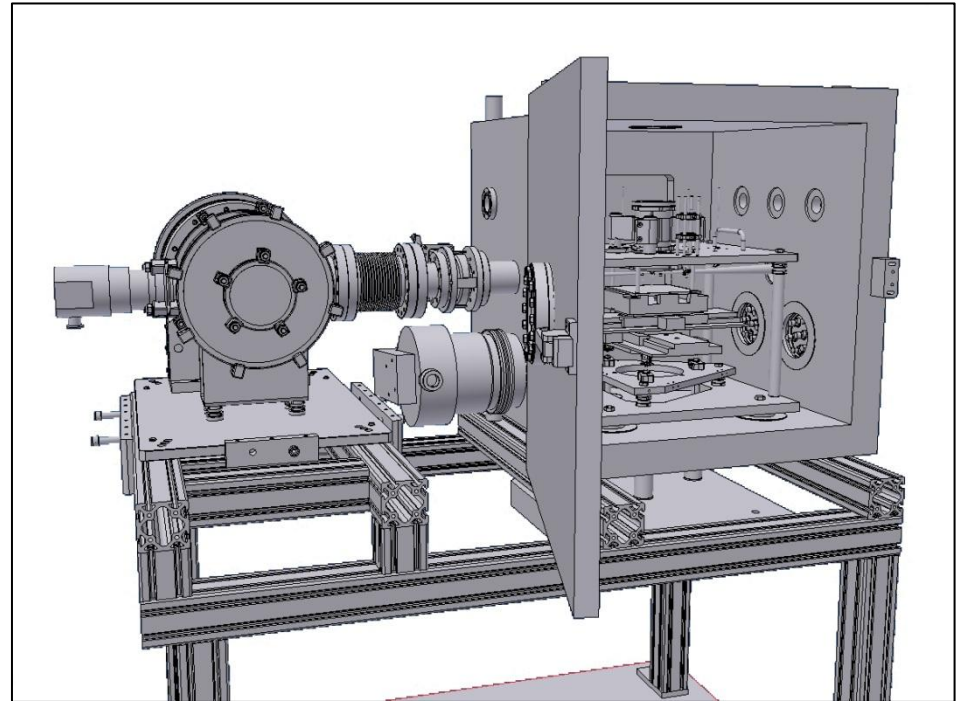
7. Conclusion & Outlook

Conclusion:

- Process window can be opened for best case scenario in the present setup
- The main limiting component is the detector, no suitable detector available to date
- Open electrode CMOS shows promising potential to be suitable
- Extendability to 20nm possible with faster camera

Outlook:

- New defect inspection setup will be commissioned in spring 2012
- New setup offers enlarged metrology spectrum: reflectivity monitoring, dark AND bright field operation and dose monitoring



Acknowledgements & References

Acknowledgements

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References

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² *High-resolution EUV imaging tools for resist exposure and aerial, Proc. SPIE 5751, 78, 2005*

³ *AlGaIn photo-detectors for applications in the extreme ultraviolet (EUV) wavelength range, Proc. of SPIE Vol. 7003 70030N-1, 2008*

⁴ *EUV and Soft X-Ray Quantum Efficiency Measurements of a Thinned Back-Illuminated CMOS Active Pixel Sensor, IEEE Electron Device Letters, Vol. 32. No. 3, 2011*

⁵ *Quantum efficiency determination of a novel CMOS design for fast imaging applications in the extreme ultraviolet, IEEE Transactions on Electron Devices, accepted*

Thank you for your attention!

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